Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	(("6390690") or ("6600853") or ("4465333") or ("6257771") or ("6623177") or ("20030128933") or ("20030219217")).PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:12
S2	0	("2003/0128933").URPN.	USPAT	OR	OFF	2004/11/30 12:03
S3	1972	(drill$1 or drilling$1) and (plate$1 or plating$1) and (etch or etching) and ((insulate$1 or insulating$1) same (epoxy or resin or adhesive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:06
S4	71	S3 and (((electo or electric$3) and (opto$4 or optical)) with (via$1 or hole$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:08
S5	88	S3 and (((electo or electric$3) and (opto$4 or optical)) with (via$1 or hole$1 or channel$1 or path$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:08
S6	1522	S3 and (copper with (clad$1 or cladding$1 or laminate$1 or layer$1 or layering$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:10
S7	54	S6 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 12:10
S8	19	("3351816").URPN.	USPAT	OR	OFF	2004/11/30 12:11
S9	9	("RE27089").URPN.	USPAT	OR	OFF	2004/11/30 12:14
S10	70	("5282312").URPN.	USPAT	OR	OFF	2004/11/30 13:47
S11	19	("3351816").URPN.	USPAT	OR	OFF	2004/11/30 14:33
S12	9	("5386627").URPN.	USPAT	OR	OFF	2004/11/30 15:04
S13	27	("5421083").URPN.	USPAT	OR	OFF	2004/11/30 15:21
S14	0	("6787710").URPN.	USPAT	OR	OFF	2004/11/30 15:30
S15	3	("5421083" | "5502893" | "5949030").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:30

S16	23	("4050756" | "4191789" | "4268956" | "4373363" | "4438561" | "4617730" | "4713494" | "4788767" | "4908940" | "4935584" | "5027253" | "5224265" | "5232548" | "5282312").PN. OR ("5386627").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:31
S17	33	("4642889" | "4675788" | "4776087" | "5233133" | "5323534" | "5363550").PN. OR ("5421083").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:32
S18	47	(US-20030128933-$ or US-20010010250-$ or US-20020016018-$ or US-20030129383-$ or US-20030178229-$ or US-20040109628-$ or US-20040109627-$ or US-20040120631-$ or US-20040145873-$ or US-20040148766-$ or US-20040212030-$).did. or (US-4153988-$ or US-5282312-$ or US-5386627-$ or US-5570504-$ or US-5640761-$ or US-5719354-$ or US-5906043-$ or US-5906042-$ or US-5962815-$ or US-6016005-$ or US-6190509-$ or US-6242286-$ or US-6499214-$ or US-6518091-$ or US-6800537-$ or US-6820330-$ or US-5421083-$ or US-6438281-$ or US-6448506-$ or US-6564454-$ or US-6629362-$ or US-6664127-$ or US-5568682-$ or US-5729897-$ or US-5744285-$ or US-5707893-$).did. or (US-5949030-$ or US-6020049-$ or US-6195883-$ or US-6303881-$ or US-6787710-$ or US-5502893-$ or US-5224265-$ or US-5232548-$).did. or (US-3351816-$ or US-RE27089-$).did.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/30 15:44
S19	21	S18 and (fiber$1 or wave$guide$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 15:44

S20	127493	(optical or opto) with (via$1 or hole$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
S21	1795	S20 and (copper with (clad$1 or cladding$1 or laminate$1 or layer$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
S22	198	S21 and ((insulation or insulating or resin) with adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:03
S23	187	S22 not S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:03
S24	171	S23 not (S4 or S5 or S7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:09
S25	43	S24 and ((optical with fiber$1) or wave$guide$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:09
S26	864	S20 and 385/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16
S27	49	S21 and 385/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/30 17:16

S28	49	(US-20010010250-$ or US-20020016018-$ or US-20030128907-$ or US-20030128933-$ or US-20030129383-$ or US-20030178229-$ or US-20040001661-$ or US-20040109627-$ or US-20040109628-$ or US-20040120631-$ or US-20040145873-$ or US-20040148766-$ or US-20040212030-$).did. or (US-4153988-$ or US-5224265-$ or US-5232548-$ or US-5282312-$ or US-5386627-$ or US-5421083-$ or US-5502893-$ or US-5568682-$ or US-5570504-$ or US-5640761-$ or US-5707893-$ or US-5719354-$ or US-5729897-$ or US-5744285-$ or US-5906042-$ or US-5906043-$ or US-5949030-$ or US-5962815-$ or US-6016005-$ or US-6020049-$ or US-6190509-$ or US-6195883-$ or US-6242286-$ or US-6303881-$ or US-6438281-$ or US-6448506-$).did. or (US-6499214-$ or US-6518091-$ or US-6564454-$ or US-6629362-$ or US-6664127-$ or US-6787710-$ or US-6800537-$ or US-6820330-$).did. or (US-3351816-$ or US-RE27089-$).did.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/12/01 12:28
S29	8	S28 and ((epoxy or resin or adhesive) same (light))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:38
S30	13	S28 and prepreg	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:39
S31	2	S28 and prepreg and ((optical with fiber$1) or wave$guide$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/01 12:39
S32	1	(("6839476") or ("6879423")).PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:13

S33	0	("6879423").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:14
S34	0	("6879423").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:14
S35	1	("20040136099").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/04 17:14
S36	393	(opto$via or (optical with via) or via$hole or (via with hole)) and (copper with laminate) and (resin with adhesive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/12 09:24
S37	14	("3546009").URPN.	USPAT	OR	ON	2005/04/12 09:28
S38	24	("3146125" | "3546009" | "3625758" | "3737339" | "3925138" | "3932689" | "3956041" | "4152477" | "4239813" | "4251649" | "4396679" | "4457952" | "4578315" | "4647631" | "4804575").PN. OR ("4927742").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 09:31
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S43	35	("4150421" | "4211603" | "4729061" | "4795693" | "4830704" | "4849284" | "5021821" | "5026624" | "5146674" | "5262280" | "5263243" | "5298117" | "5300402" | "5334487" | "5366846" | "5387493" | "5451721" | "5473120" | "5883335" | "6027858").PN. OR ("6201194").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:02
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S45	2	(("6730859") or ("6005766")).PN.	US-PGPUB; USPAT	OR	OFF	2005/04/12 10:13
S46	26	("4854038" | "5120384" | "5153986" | "5153987" | "5185502" | "5191174" | "5224265" | "5232548" | "5298685" | "5316787" | "5362534" | "5421083" | "5435057" | "5557843" | "5558928" | "5685070" | "5745333" | "5747222" | "5822856" | "5834160" | "6103135" | "6131279" | "6181004" | "6201194" | "6215372" | "6255039").PN. OR ("6832436").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:13
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S48	23	("4050756" | "4191789" | "4268956" | "4373363" | "4438561" | "4617730" | "4713494" | "4788767" | "4908940" | "4935584" | "5027253" | "5224265" | "5232548" | "5282312").PN. OR ("5386627").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:24
S49	382	S36 not (6-17)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:24
S50	360	S36 not (S37 S38 S39 S40 S41 S42 S43 S44 S45 S46 S47 S48)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:24

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S52	41	("20020050402" | "4876120" | "5218030" | "5258325" | "5346747" | "5352745" | "5426522" | "5477612" | "5517751" | "5640761" | "5677045" | "5819403" | "5821457" | "5822850" | "5824950" | "5830542" | "5950306" | "6078102" | "6092280" | "6108903" | "6114005" | "6154940" | "6163957" | "6243946" | "6274242" | "6323436" | "6329603" | "6351393" | "6352782" | "6355504" | "6373717" | "6465742" | "6580031" | "6581280" | "6673190" | "6708404" | "6722031" | "6745464" | "6748652" | "6764748" | "6774316").PN. OR ("6826830").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/12 10:38

April 12, 2005   USPTO

Displaying records #1 through 10 out of 30

Result # 1   Relevance: ○○○○○

PREVIEW

Via Punching Device for Multi-Layered Ceramic Sut

29-Jan-2005   IPCOM000037316D   Englisl

A technique is described whereby the mechanical punching of v
multi-layered ceramic substrates is controlled through the use c
independently controlled punching stations. The new via punchi
improvement of a previous system which uses only a ...

Result # 2   Relevance: ○○

PREVIEW

Minimal Metal Mask for Reactive Ion Etching Polyir

13-Feb-2005   IPCOM000055528D   Englisl

The fabrication of thin film modules of multi-layered ceramic mi
packaging chips requires the making of via holes through a ther
resin which serves as a dielectric between transmission line leve
transmission line-ground plane levels.

Result # 3   Relevance: ○○

PREVIEW

SIP: Session Initiation Protocol (RFC3261)

09-Aug-2002   IPCOM000009156D   Englisl

This document describes Session Initiation Protocol (SIP), an af
control (signaling) protocol for creating, modifying, and termina
with one or more participants. These sessions include Internet t
multimedia distribution, and ...

Result # 4   Relevance: ○

PREVIEW

RETENTION OF PHOSPHORUS IN SILICON BENEATI
SILICIDE CONTACTS DURING HIGH TEMPERATURE

19-Oct-2001   IPCOM000005621D   Englisl

After metal contacts and short-range interconnects are deposite
there is often the need to carry out processing at high temperal
Compound formation, grain size enhancement, contact improve
glass reflow for tapering of via holes in thick doped ...

Result # 5   Relevance: ○

PREVIEW

Manufacturing process to fabricate co-planar multi
printed circuit boards

20-Jun-2003   IPCOM000014863D   Englisl

A manufacturing process for insuring co-planarity of epoxy print
boards fabricated with more than one level on a side having difi
surface dimensions is described. Individual layers of printed circ
material (comprised of differing circuit layout ...

Result # 6   Relevance: ○

PREVIEW

Method for Forming Wiring Patterns and Vias on a
Substrates

29-Jan-2005   IPCOM000036834D   Englisl

This article describes a new method of defining wiring patterns

pure metals or metallic alloys on various ceramic greensheets, |
fired ceramic substrates, or polymer surfaces. The disclosed prc
capability for obtaining higher resolution ...

Result # 7   Relevance:

PREVIEW

Method for Structural Characterization of Bi-Layer for Use in Personal Care Products via Microscopy a Analysis

14-Dec-2004   IPCOM000033526D   Englisl

A methodology has been developed to characterize the structur
multi-layer absorbent materials. The method is able to detect a
z-distribution of polypropylene and cellulose components. Outpi
method was used to determine that the ...

Result # 8   Relevance:

PREVIEW

Single-Crystal Silicon Embedded With Insulated Co Wires

28-Jan-2005   IPCOM000036028D   Englisl

In packaging technology, a generic problem is that the packagir
tend to have a different thermal expansion coefficient from that
Consequently, upon thermal cycling during operation a shear st
on those solder balls that join the chip and ...

Result # 9   Relevance:

PREVIEW

Network File System (NFS) version 4 Protocol (RF(

30-Apr-2003   IPCOM000012311D   Englisl

The Network File System (NFS) version 4 is a distributed filesys
which owes heritage to NFS protocol version 2, RFC 1094, and '
1813. Unlike earlier versions, the NFS version 4 protocol suppoi
file access while integrating support ...

Result # 10   · Relevance:

PREVIEW

Towards Requirements for IP Routers (RFC1716)

12-Sep-2000   IPCOM000003963D   Englisl

The goal of this work is to replace RFC-1009, Requirements for
Gateways ([INTRO:1]) with a new document.

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Search query: via AND holes AND layered

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Secu

April 12, 2005   USPTO

Search

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Publish Disclosure

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Lookup

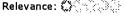Displaying records #11 through 20 out of 30

Result # 11   Relevance: ○○○○

PREVIEW

Silver halide photographic light-sensitive material super-rapid processing

12-Sep-2000   IPCOM000000670D   Englisl

A silver halide photographic light-sensitive material comprising having the first photographic structural layer comprising one or a side of the support and the second photographic structural la) one or more layers on the other side of ...

Result # 12   Relevance: ○○○○

PREVIEW

Exhalation duct

12-Sep-2000   IPCOM000000800D   Englisl

An exhalation duct is formed from a gas impermeable covering acer material extending through the length of the duct to define cylindrical opening. A lower end of the duct is formed with a plu exhalation holes or openings in the covering ...

Result # 13   Relevance: ○○○○

PREVIEW

Efficient Two Layered Organic Photovoltaic Device

03-Mar-2005   IPCOM000085960D   Englisl

For organic light-absorbing species at a solid-solid interface, eff photoactivated free-carrier generation has so far been limited b (silver halide photography) or by the requirement of very high ((electrophotography). Yet the solar ...

Result # 14   Relevance: ○○○○

PREVIEW

NFS version 4 Protocol (RFC3010)

17-Aug-2001   IPCOM000005202D   Englisl

NFS (Network File System) version 4 is a distributed file systerr owes heritage to NFS protocol versions 2 [RFC1094] and 3 [RF(earlier versions, the NFS version 4 protocol supports traditional while integrating support for file ...

Result # 15   Relevance: ○○○○

PREVIEW

Requirements for Internet gateways - draft (RFC0!

13-Jul-2001   IPCOM000004983D   Englisl

The following sections are intended as an introduction and back those unfamiliar with the DARPA Internet architecture and the I gateway model. General background and discussion on the Inte architecture and supporting protocol suite can be found in ...

Result # 16   Relevance: ○○○○

PREVIEW

Cylindrical keyed coupling for composite propulsio

12-Sep-2000   IPCOM000001626D   Englisl

A coupling for a torsional drive includes a rotatable shaft, an ou which has a keyway comprising a half-round groove. A rotabli around the shaft and coaxial with the shaft has an inner surface

a second keyway, the second keyway also ...

Result # 17   Relevance: ⬡⬡⬡⬡⬡

Softshell protective mask

PREVIEW

12-Sep-2000   IPCOM000001350D   Englisl

Form-fitting, comfortable, soft-shell protective apparel, commor
mask, for protecting the head, upper body and respiratory tract
chemical/biological agents and toxins and radioactive particles.
easy-to-put-on, heat and moisture-dissipating ...

Result # 18   Relevance: ⬡⬡⬡⬡⬡

**Advice for Internet Subnetwork Designers AUTHOF
(RFC3819)**

PREVIEW

09-Jul-2004   IPCOM000029724D   Englisl

This document provides advice to the designers of digital comm
equipment, link-layer protocols, and packet-switched local netw
(collectively referred to as subnetworks), who wish to support t
protocols but may be unfamiliar with the Internet ...

Result # 19   Relevance: ⬡⬡⬡⬡⬡

**Method for high-density semiconductor packages f
substrates fabricated on continuous reels**

PREVIEW

16-Jun-2004   IPCOM000029161D   Englisl

Disclosed is a method for high-density semiconductor packages
substrates fabricated on continuous reels. Benefits include impr
functionality, improved performance, improved reliability, and ii

Result # 20   Relevance: ⬡⬡⬡⬡⬡

Requirements for IP Version 4 Routers (RFC1812)

PREVIEW

13-Sep-2000   IPCOM000004069D   Englisl

This memo replaces for RFC 1716, "Requirements for Internet
Gateways" ([INTRO:1]).

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Search query: via AND holes AND layered

New search | Modify this search | Search within current results

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Search

- Full Text
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Publish

- Publish Disclosure

My IP.com

- Manage Account
- Prior Purchases
- Prior Disclosures
- Events
- Main Page
- Support
- Logout

Fingerprint Lookup

[Lookup]

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Result # 21   Relevance: ◯

PREVIEW

Transparent Content Negotiation in HTTP (RFC229!

13-Sep-2000   IPCOM000002858D   Englisl

HTTP allows web site authors to put multiple versions of the sar under a single URL. Transparent content negotiation is an exter negotiation mechanism, layered on top of HTTP, for automatica best version when the URL is accessed. This ...

Result # 22   Relevance: ◯

PREVIEW

Split barrel insulation displacing connector

11-Sep-2000   IPCOM000000001D   Englisl

A split-barrel connector terminal is presented wherein a wire co terminal is released as a new wire is being connected. This feat by aperture (13) located a predetermined distance from the wir of slot (12). When insertion tool (51) ...

Result # 23   Relevance: ◯

PREVIEW

Some Internet Architectural Guidelines and Philos((RFC3439)

11-Dec-2002   IPCOM000010524D   Englisl

This document extends RFC 1958 by outlining some of the phil(guidelines to which architects and designers of Internet backboi should adhere. We describe the Simplicity Principle, which state complexity is the primary mechanism that impedes ...

Result # 24   Relevance: ◯

PREVIEW

Requirements for Internet gateways (RFC1009)

12-Sep-2000   IPCOM000001812D   Englisl

The following material is intended as an introduction and backg unfamiliar with the Internet architecture and the Internet gatew General background and discussion on the Internet architecture supporting protocol suite can be found in the DDN ...

Result # 25   Relevance: ◯

PREVIEW

Performance Enhancing Proxies Intended to Mitiga Related Degradations (RFC3135)

21-Aug-2001   IPCOM000005319D   Englisl

This document is a survey of Performance Enhancing Proxies (P employed to improve degraded TCP performance caused by cha specific link environments, for example, in satellite, wireless W/ wireless LAN environments. Different types of ...

Result # 26   Relevance: ◯

PREVIEW

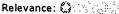### SDP: Session Description Protocol (RFC2327)

13-Sep-2000   IPCOM000002894D   Englisl

This document defines the Session Description Protocol, SDP. S for describing multimedia sessions for the purposes of session a

session invitation, and other forms of multimedia session initiat

---

Result # 27   Relevance: ⬡ ⟨⟩⟨⟩

PREVIEW

Report of IAB Workshop on Security in the Interne Architecture - February 8-10, 1994 (RFC1636)

12-Sep-2000   IPCOM000002472D   Englisl

This document is a report on an Internet architecture workshop the IAB and held at USC Information Sciences Institute on Febr 1994. This workshop generally focused on security issues in the architecture.

Result # 28   Relevance: ⬡ ⟨⟩⟨⟩

PREVIEW

Use of IPsec Transport Mode for Dynamic Routing

25-Sep-2004   IPCOM000031435D   Englisl

IPsec can secure the links of a multihop network to protect com between trusted components, e.g., for a secure virtual network or virtual private network (VPN). Virtual links established by IPs can conflict with routing and forwarding ...

Result # 29   Relevance: ⬡ ⟨⟩⟨⟩

PREVIEW

Loader Debugger Protocol (RFC0909)

13-Sep-2000   IPCOM000003959D   Englisl

Result # 30   Relevance: ⬡ ⟨⟩⟨⟩

PREVIEW

Heterojunction D.sup.- (or A.sup.+) millimeter and submillimeter wave detector

12-Sep-2000   IPCOM000000095D   Englisl

A solid state detector for use in detecting submillimeter and mil radiation. The solid state detector comprises a semiconductor s alternating thin epitaxial layers of GaAs and AlGaAs doped with having the same conductivity type. Because ...

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Search query: via AND holes AND layered

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